

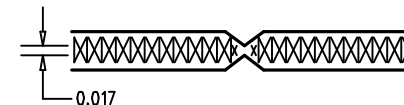
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.07	2	+	NPLTD
0.035	31	×	PLTD
0.015	138	□	PLTD
0.094	9	◇	PLTD
0.055	15	⊗	PLTD
0.125	4	⊗	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE READ ME FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INT	DATE		
CHECK			TITLE: Fabrication Drawing 16 BIT 250 KSPS ADC	
DESIGN	KIM T.	12-10-01		
ENGR	DEREK R.	12-10-01	SIZE A DEMO DC416A-2*LTC1864CMS8 REV. A	
SCALE = NONE			DES- 0000	SHT 1 of 1